

International IOR Rectifier HEXFET® POWER MOSFET

Provisional Data Sheet No. PD-9.552B

JANTX2N6845

JANTXV2N6845

[REF:MIL-PRF-19500/563]

[GENERIC:IRFF9120]

P-CHANNEL

-100 Volt, 0.60Ω HEXFET

HEXFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry achieves very low on-state resistance combined with high transconductance.

HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, and high energy pulse circuits, and virtually any application where high reliability is required.

Product Summary

Part Number	BV _{DSS}	R _{DS(on)}	I _D
JANTX2N6845	-100V	0.60Ω	-4.0A
JANTXV2N6845			

Features:

- Avalanche Energy Rating
- Dynamic dv/dt Rating
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed

勝特力材料 886-3-5753170
勝特力电子(上海) 86-21-54151736
勝特力电子(深圳) 86-755-83298787
[Http://www.100y.com.tw](http://www.100y.com.tw)

Absolute Maximum Ratings

	Parameter	JANTX2N6845, JANTXV2N6845	Units
I _D @ V _{GS} = -10V, T _C = 25°C	Continuous Drain Current	-4.0	A
I _D @ V _{GS} = -10V, T _C = 100°C	Continuous Drain Current	-2.6	
I _{DM}	Pulsed Drain Current ①	-16	
P _D @ T _C = 25°C	Max. Power Dissipation	20	W
	Linear Derating Factor	0.16	W/K ⑤
V _{GS}	Gate-to-Source Voltage	±20	V
dv/dt	Peak Diode Recovery dv/dt ③	-5.0	V/ns
T _J	Operating Junction	-55 to 150	°C
T _{STG}	Storage Temperature Range		
	Lead Temperature	300 (0.063 in. (1.6mm) from case for 10.5 seconds)	
	Weight	0.98 (typical)	g

JANTX2N6845, JANTXV2N6845 Device

Electrical Characteristics @ Tj = 25°C (Unless Otherwise Specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BVDSS	Drain-to-Source Breakdown Voltage	-100	—	—	V	VGS = 0V, ID = -1.0 mA
ΔBVDSS/ΔTj	Temperature Coefficient of Breakdown Voltage	—	-0.10	—	V/°C	Reference to 25°C, ID = -1.0 mA
RDS(on)	Static Drain-to-Source On-State Resistance	—	—	0.60	Ω	VGS = -10V, ID = -2.6A④
		—	—	0.69	Ω	VGS = -10V, ID = -4.0A
VGS(th)	Gate Threshold Voltage	-2.0	—	-4.0	V	VDS = VGS, ID = -250μA
gfs	Forward Transconductance	1.25	—	—	S (Ω)	VDS > -15V, IDS = -2.6A ④
IDSS	Zero Gate Voltage Drain Current	—	—	-25	μA	VDS = 0.8 x Max Rating, VGS = 0V
		—	—	-250	μA	VDS = 0.8 x Max Rating, VGS = 0V, Tj = 125°C
IGSS	Gate-to-Source Leakage Forward	—	—	-100	nA	VGS = -20V
IGSS	Gate-to-Source Leakage Reverse	—	—	100	nA	VGS = 20V
Qg	Total Gate Charge	4.3	—	16.3	nC	VGS = -10V, ID = -4.0A
Qgs	Gate-to-Source Charge	1.3	—	4.7	nC	VDS = Max. Rating x 0.5
Qgd	Gate-to-Drain ("Miller") Charge	1.0	—	9.0	nC	see figures 6 and 13
td(on)	Turn-On Delay Time	—	—	60	ns	VDD = -50V, ID = -4.0A, RG = 7.5Ω, VGS = -10V
tr	Rise Time	—	—	100	ns	
td(off)	Turn-Off Delay Time	—	—	50	ns	
tf	Fall Time	—	—	70	ns	see figure 10
LD	Internal Drain Inductance	—	5.0	—	nH	Measured from the drain lead, 6mm (0.25 in.) from package to center of die.
LS	Internal Source Inductance	—	15	—	nH	Measured from the source lead, 6mm (0.25 in.) from package to source bonding pad.
Ciss	Input Capacitance	—	380	—	pF	VGS = 0V, VDS = -25V
Coss	Output Capacitance	—	170	—	pF	f = 1.0 MHz
Crss	Reverse Transfer Capacitance	—	45	—	pF	see figure 5

Source-Drain Diode Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
IS	Continuous Source Current (Body Diode)	—	—	-4.0	A	Modified MOSFET symbol showing the integral reverse p-n junction rectifier.
ISM	Pulse Source Current (Body Diode) ①	—	—	-16	A	
VSD	Diode Forward Voltage	—	—	-4.8	V	Tj = 25°C, IS = -4.0A, VGS = 0V ④
trr	Reverse Recovery Time	—	—	200	ns	Tj = 25°C, IF = -4.0A, di/dt ≤ -100A/μs
QRR	Reverse Recovery Charge	—	—	3.1	μC	VDD ≤ -50V ④
ton	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by LS + LD.				

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
RthJC	Junction-to-Case	—	—	6.25	K/W	
RthJA	Junction-to-Ambient	—	—	175		Typical socket mount

JANTX2N6845, JANTXV2N6845 Device

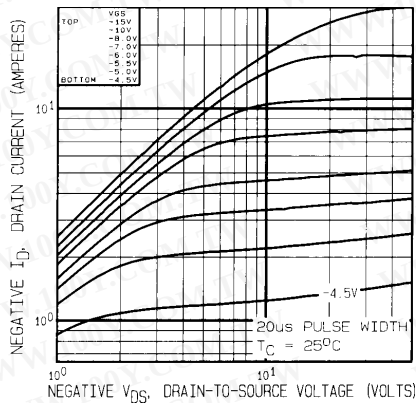


Fig. 1 — Typical Output Characteristics
 $T_c = 25^\circ\text{C}$

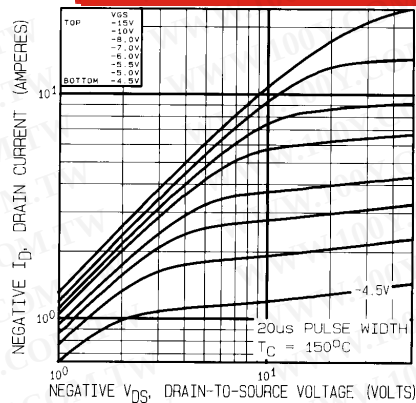


Fig. 2 — Typical Output Characteristics
 $T_c = 150^\circ\text{C}$

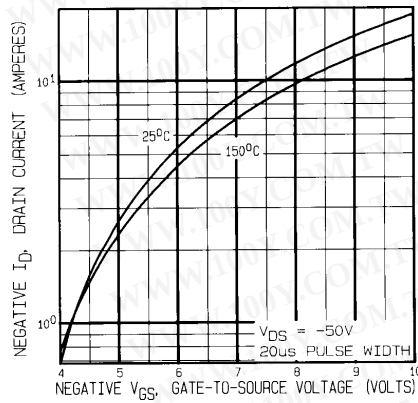


Fig. 3 — Typical Transfer Characteristics

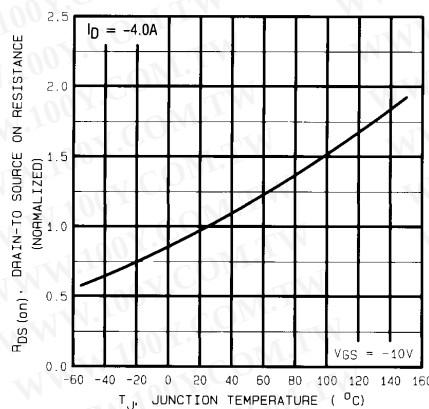


Fig. 4 — Normalized On-Resistance Vs. Temperature

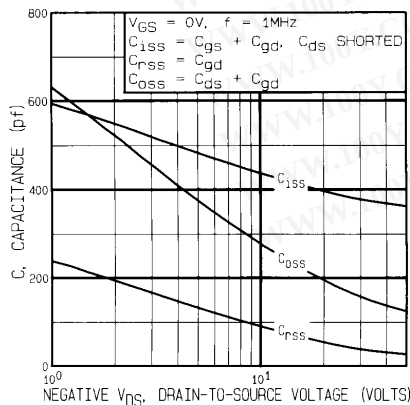


Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage

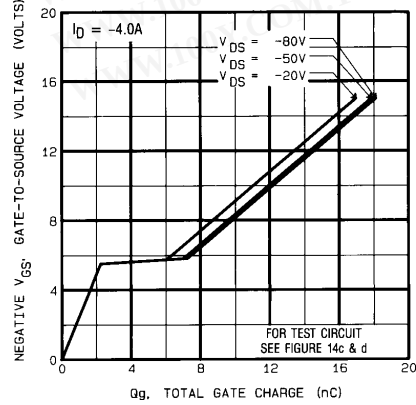


Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage

JANTX2N6845, JANTXV2N6845 Device

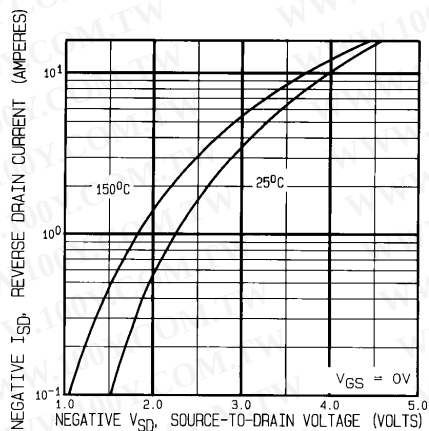


Fig. 7 — Typical Source-to-Drain Diode Forward Voltage

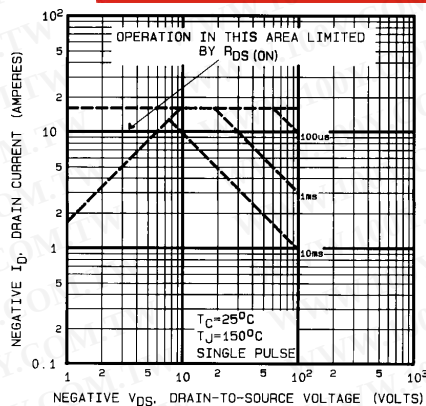


Fig. 8 — Maximum Safe Operating Area

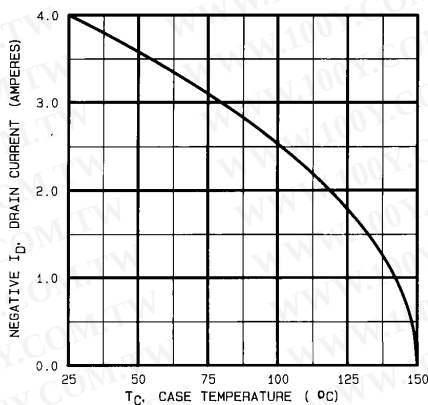


Fig. 9 — Maximum Drain Current Vs. Case Temperature

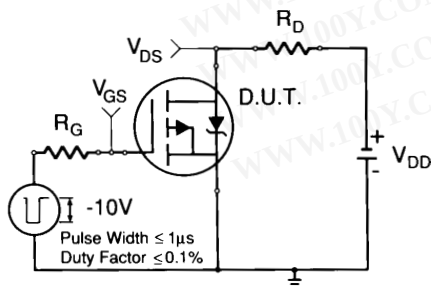


Fig. 10a — Switching Time Test Circuit

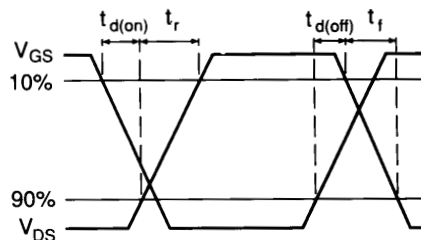


Fig. 10b — Switching Time Waveforms

JANTX2N6845, JANTXV2N6845 Device

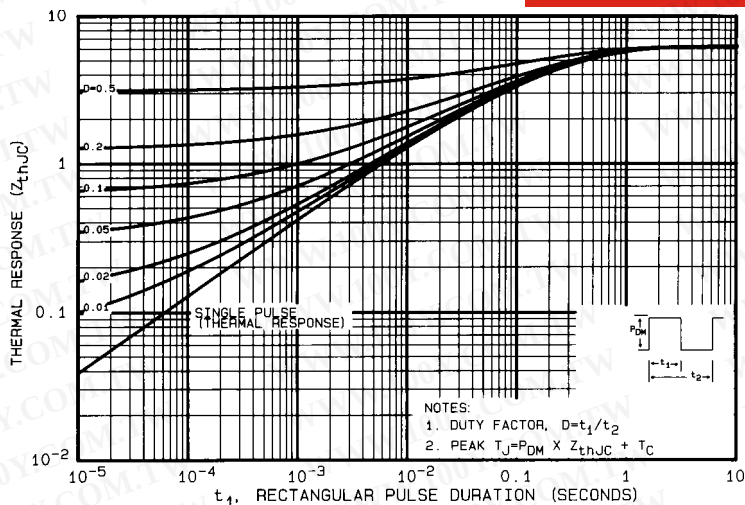


Fig. 11 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

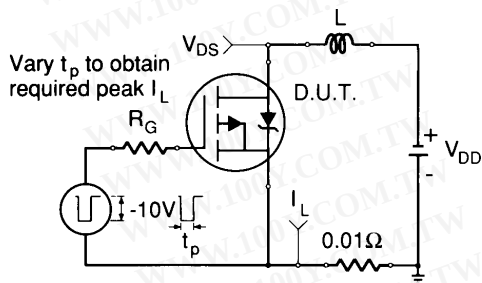


Fig. 12a — Unclamped Inductive Test Circuit

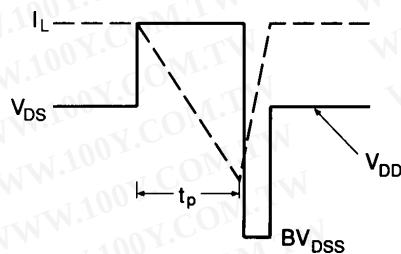


Fig. 12b — Unclamped Inductive Waveforms

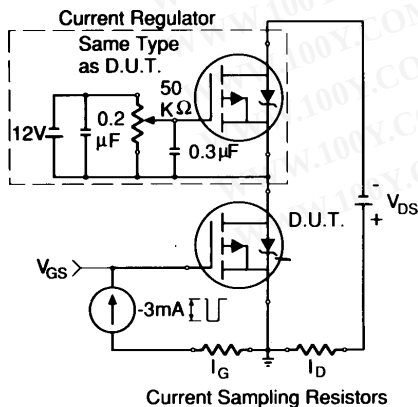


Fig. 13a — Gate Charge Test Circuit

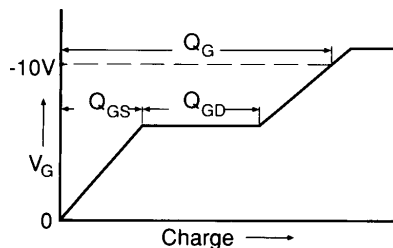


Fig. 13b — Basic Gate Charge Waveform

JANTX2N6845, JANTXV2N6845 Device

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
(see figure 11)
- ② @ $V_{DD} = -25V$, Starting $T_J = 25^\circ C$,
 $EAS = [0.5 * L * (I_L^2) * [BVDSS/(BVDSS - V_{DD})]]$
 Peak $I_L = -4.0A$, $V_{GS} = -10V$, $25 \leq R_G \leq 200\Omega$
- ③ $ISD \leq -4.0A$, $di/dt \leq -110A/\mu s$,
 $V_{DD} \leq BVDSS$, $T_J \leq 150^\circ C$
- ④ Pulse width $\leq 300 \mu s$; Duty Cycle $\leq 2\%$
- ⑤ $K/W = ^\circ C/W$
 $W/K = W/^\circ C$

Case Outline and Dimensions — TO-205AF (Modified TO-39)

